

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Please amend the claims as follows:

1-14. (Canceled).

15. (Currently Amended) A device, comprising:

a coolant;

a first structure having a first thermal resistance and including particles having an average diameter greater than about 50  $\mu\text{m}$  to convert some of the coolant from liquid to vapor;

a second structure around the first structure to wet the first structure with the coolant from multiple sides and having a second thermal resistance that is greater than the first thermal resistance; and

a plurality of outer walls to enclose the coolant, the first structure, and the second structure in an air tight manner.

16. (Original) The device of claim 15, wherein the average diameter of the particles is less than about 500  $\mu\text{m}$ .

17. (Original) The device of claim 15, wherein the second structure has a higher thermal resistance than the first structure.

18. (Original) The device of claim 15, wherein the second structure includes a wire mesh, sintered particles, fibers, or axial grooves.

19. (Original) The device of claim 15, wherein a top surface of the second structure extends beyond a top surface of the first structure by an amount sufficient to ensure pooling of the coolant on the top surface of the first structure.
20. (Previously Presented) A system, comprising:  
a heat pipe, including:  
a boiling structure having a first thermal resistivity, and  
a wick structure around a perimeter of the boiling structure and having a second thermal resistivity that is significantly greater than the first thermal resistivity; and  
a fan to move air across at least a portion of the heat pipe.
21. (Original) The system of claim 20, wherein the boiling structure includes particles having an average diameter of about 300  $\mu\text{m}$ .
- 22-24. (Canceled).
25. (New) A device, comprising:  
a boiling structure formed of a first porous material to convert a coolant from liquid to vapor and having a first thermal resistance; and  
a wick structure formed of a second porous material surrounding the boiling structure to bring the coolant to the boiling structure and having a second thermal resistance that is higher than the first thermal resistance of the boiling structure.
26. (New) The device of claim 25, wherein boiling structure includes particles having an average diameter greater than about 50  $\mu\text{m}$ .

27. (New) The device of claim 26, wherein the average diameter is less than about 500  $\mu\text{m}$ .
28. (New) The device of claim 25, wherein the wick structure surrounds the boiling structure on all sides and does not extend over a top of the boiling structure.
29. (New) The device of claim 25, wherein a top surface of the wick structure extends above a top surface of the boiling structure by about 0.1 mm or greater.
30. (New) The device of claim 25, wherein the first thermal resistance is about 0.1  $^{\circ}\text{C}/\text{W}$  for a 1  $\text{cm}^2$  area.
31. (New) The device of claim 26, wherein the particles include copper.
32. (New) The device of claim 25, wherein the wick structure includes a wire mesh, sintered particles, fibers, or axial grooves.
33. (New) A heat pipe, comprising:  
a boiling structure formed of a porous material;  
a wick formed of another porous material surrounding all sides of the boiling structure and having a lower capacity for heat transfer per unit area than the boiling structure; and  
a casing enclosing the boiling structure and the wick.

34. (New) The heat pipe of claim 33, wherein the boiling structure has a mean feature size greater than about 50  $\mu\text{m}$ .
35. (New) The heat pipe of claim 33, wherein a top surface of the wick extends beyond a top surface of the boiling structure.
36. (New) The heat pipe of claim 33, wherein a thermal resistivity of the boiling structure is less than about 0.1  $^{\circ}\text{C}\text{-cm}^2/\text{W}$ .
37. (New) The heat pipe of claim 33, wherein a thermal resistivity of the wick is greater than about 0.1  $^{\circ}\text{C}\text{-cm}^2/\text{W}$ .
38. (New) The heat pipe of claim 33, wherein the boiling structure, the wick, and the casing include copper.